

# MBRP40030CTL

## POWERTAP II Switch-mode Power Rectifier

This state-of-the-art SWITCHMODE Power Rectifier uses the Schottky Barrier principle with a platinum barrier metal.

### Features

- Dual Diode Construction; May Be Paralleled for Higher Current Output
- Guard-Ring for Stress Protection
- Low Forward Voltage Drop
- 150°C Operating Junction Temperature
- Recyclable Epoxy
- Improved Mechanical Ratings
- Pb-Free Package is Available\*

### Mechanical Characteristics

- Case: Epoxy, Molded with metal heatsink base
- Weight: 80 grams (Approximately)
- Finish: All External Surfaces Corrosion Resistant
- Top Terminal Torque: 25–40 lb-in Max
- Base Plate Torques: See procedure Given in the Package Outline Section

### MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	$V_{RRM}$		V
Working Peak Reverse Voltage	$V_{RWM}$		
DC Blocking Voltage	$V_R$	30	
Average Rectified Forward Current (At Rated $V_R$ , $T_C = 100^\circ\text{C}$ )	$I_{F(AV)}$	200 400	A Per Leg Per Device
Peak Repetitive Forward Current, (At Rated $V_R$ , Square Wave, 20 kHz, $T_C = 100^\circ\text{C}$ )	$I_{FRM}$	200	A
Non-Repetitive Peak Surge Current (Surge Applied at Rated Load Conditions Halfwave, Single Phase, 60 Hz)	$I_{FSM}$	1500	A
Peak Repetitive Reverse Surge Current (2.0 $\mu\text{s}$ , 1.0 kHz)	$I_{RRM}$	2.0	A
Storage Temperature Range	$T_{stg}$	-55 to +150	$^\circ\text{C}$
Operating Junction Temperature	$T_J$	-55 to +150	$^\circ\text{C}$
Voltage Rate of Change (Rated $V_R$ )	$dv/dt$	10,000	V/ $\mu\text{s}$

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

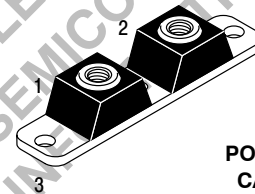
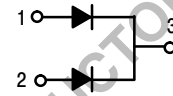
\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.



ON Semiconductor®

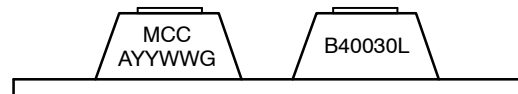
[www.onsemi.com](http://www.onsemi.com)

LOW  $V_F$  SCHOTTKY  
BARRIER RECTIFIER  
400 AMPERES, 30 VOLTS



POWERTAP II  
CASE 357C  
PLASTIC

### MARKING DIAGRAM



B40030L = Specific Device Code  
MCC = Mold Compound Code  
A = Assembly Location  
YY = Year  
WW = Work Week  
G = Pb-Free Package

### ORDERING INFORMATION

Device	Package	Shipping
MBRP40030CTL	POWERTAP II	25 Units/Tray
MBRP40030CTLG	POWERTAP II (Pb-Free)	25 Units/Tray

# MBRP40030CTL

## THERMAL CHARACTERISTICS

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction-to-Case (Note 1)	$R_{\theta JC}$	0.4	$^{\circ}C/W$

## ELECTRICAL CHARACTERISTICS

Maximum Instantaneous Forward Voltage (Note 2) ( $i_F = 200$ Amps, $T_C = +25^{\circ}C$ ) ( $i_F = 200$ Amps, $T_C = +100^{\circ}C$ )	$V_F$	0.5 0.41	V
Maximum Instantaneous Reverse Current (Note 2) (Rated dc Voltage, $T_C = +25^{\circ}C$ ) (Rated dc Voltage, $T_C = +100^{\circ}C$ )	$I_R$	20 1000	mA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Rating applies when surface mounted on the minimum pad size recommended.
- Pulse Test: Pulse Width = 300  $\mu s$ , Duty Cycle  $\leq 2\%$ .

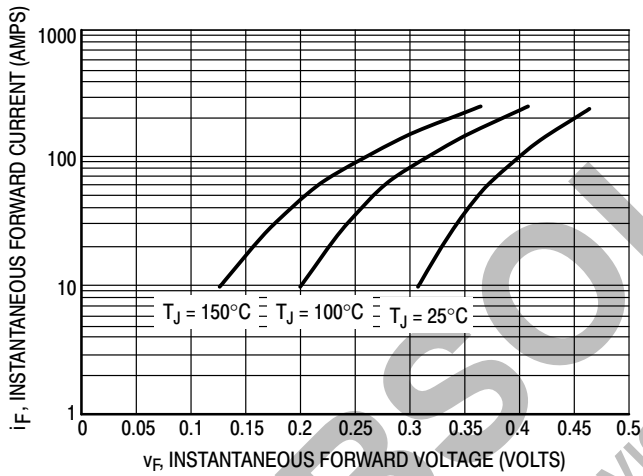


Figure 1. Typical Instantaneous Forward Voltage

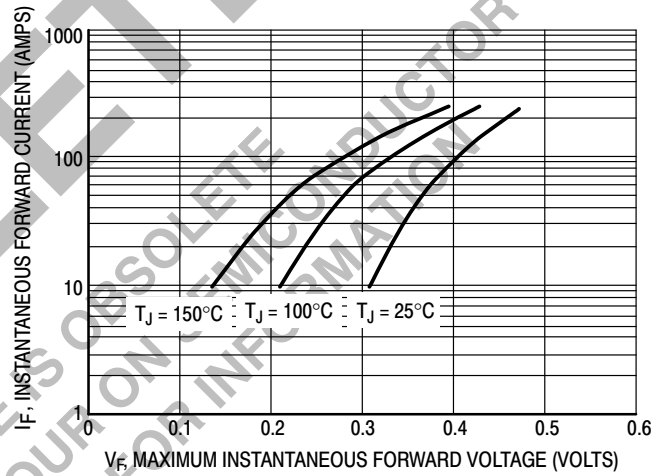


Figure 2. Maximum Instantaneous Forward Voltage

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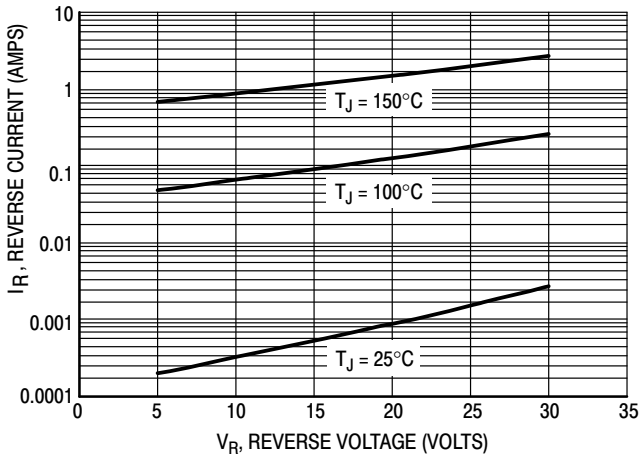


Figure 3. Typical Reverse Current

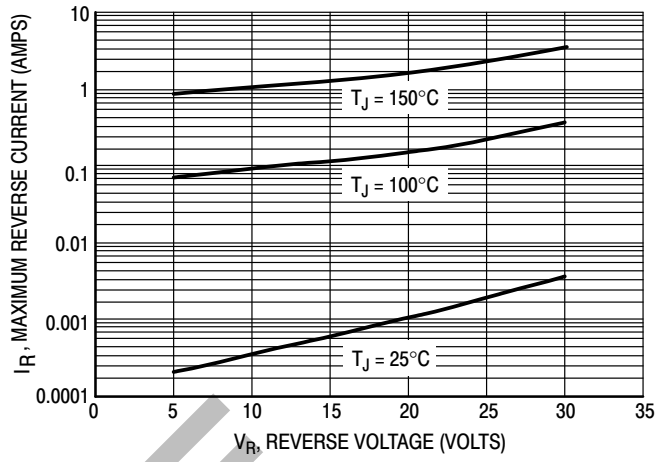


Figure 4. Maximum Reverse Current

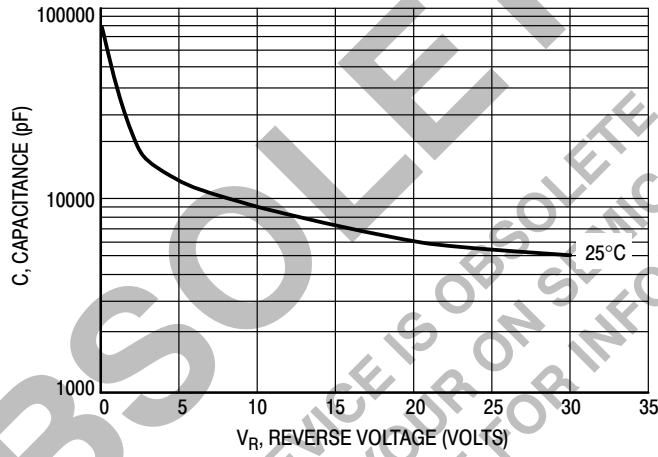


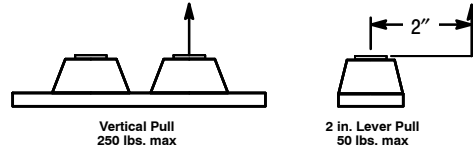
Figure 5. Typical Capacitance

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## MAXIMUM MECHANICAL RATINGS

Terminal Penetration:	0.235 max
Terminal Torque:	25-40 in-lb max
Mounting Torque - Outside Holes:	30-40 in-lb max
Mounting Torque - Center Hole:	8-10 in-lb max
Seating Plane Flatness	1 mil per in. (between mounting holes)

POWERTAP MECHANICAL DATA  
APPLIES OVER OPERATING TEMPERATURE



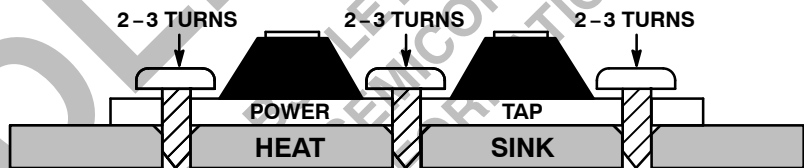
Note: While the POWERTAP is capable of sustaining these vertical and levered tensions, the intimate contact between POWERTAP and heat sink may be lost. This could lead to thermal runaway. The use of very flexible leads is recommended for the anode connections. Use of thermal grease is highly recommended.

## MOUNTING PROCEDURE

The POWERTAP package requires special mounting considerations because of the long longitudinal axis of the copper heat sink. It is important to follow the proper tightening sequence to avoid warping the heat sink, which can reduce thermal contact between the POWERTAP and heat sink.

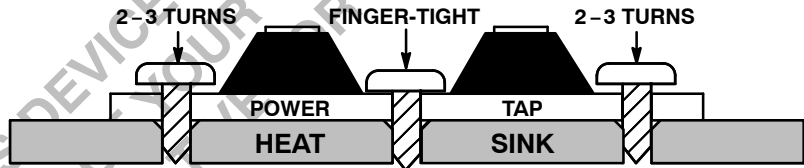
### STEP 1:

Locate the POWERTAP on the heat sink and start mounting bolts into the threads by hand (2 or 3 turns).



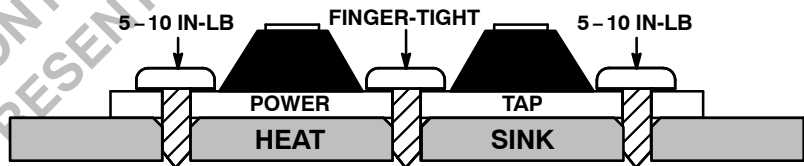
### STEP 2:

Finger tighten the center bolt. The bolt may catch on the threads of the heat sink so it is important to make sure the face of the bolt or washer is in contact with the surface of the POWERTAP.



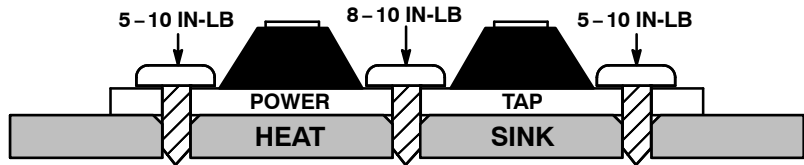
### STEP 3:

Tighten each of the end bolts between 5 to 10 in-lb.



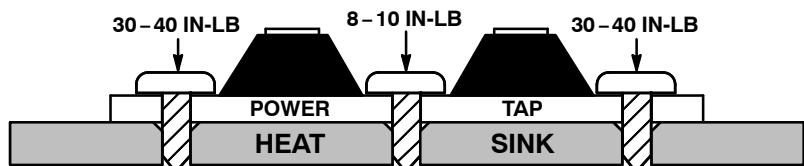
### STEP 4:

Tighten the center bolt between 8 to 10 in-lb.



### STEP 5:

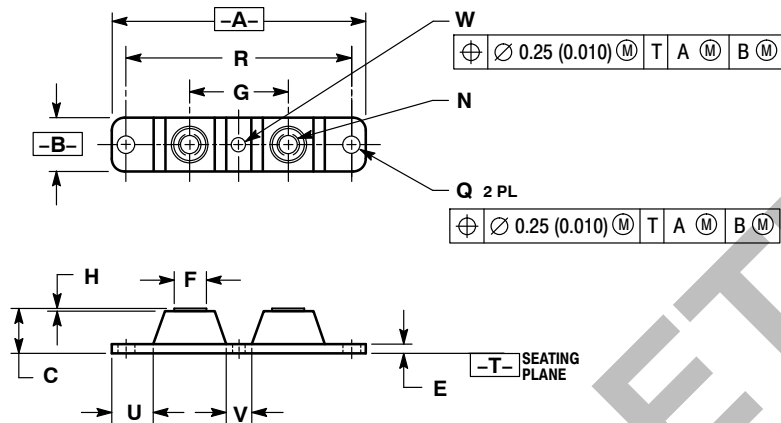
Finally, tighten the end bolts between 30 to 40 in-lb.



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## PACKAGE DIMENSIONS

CASE 357C-03  
 POWERTAP  
 PLASTIC PACKAGE  
 ISSUE E



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. TERMINAL PENETRATION: 5.97 (0.235) MAXIMUM.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	3.450	3.635	87.63	92.33
B	0.700	0.810	17.78	20.57
C	0.615	0.640	15.63	16.26
E	0.120	0.130	3.05	3.30
F	0.435	0.445	11.05	11.30
G	1.370	1.380	34.80	35.05
H	0.007	0.030	0.18	0.76
N	1/4-20UNC-2B	1/4-20UNC-2B		
Q	0.270	0.285	6.86	7.23
R	31.50 BSC		80.01 BSC	
U	0.600	0.630	15.24	16.00
V	0.330	0.375	8.39	9.52
W	0.170	0.190	4.32	4.82

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